

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc1682cs8-3.3#pbf

(Engineering Calculation)

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TOTAL MASS (g) : 0.073226

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001914 | 1000000 | 26138.3105469 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.023653 | 975000 | 323014.34375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000582 | 24000 | 7948.01318359 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000007 | 300 | 95.5946578979 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000017 | 700 | 232.158462524 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.024259 | 1000000 | 331290.09375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001477 | 1000000 | 20168.4511719 | | |
| | | External Plating Total: | | | | 0.001477 | 1000000 | 20168.4511719 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000194 | 1000000 | 2649.33740234 | | |
| Internal Plating Total: | | | | 0.000194 | 1000000 | 2649.33740234 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000669 | 750000 | 9136.11816406 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000223 | 250000 | 3045.37255859 | | |
| Die Attach Total: | | | | 0.000892 | 1000000 | 12181.4902344 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006657 | 150000 | 90910.5234375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036392 | 820000 | 496982.96875 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001110 | 25000 | 15158.5810547 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000222 | 5000 | 3031.71655273 | | |
| | | Encapsulation Total: | | | | 0.044381 | 1000000 | 606083.8125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000109 | 1000000 | 1488.54541016 | | |
| | | | | | TOTAL MASS (g) : | 0.073226 | | |